



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Examiner:

Ha T. Nguyen

Serial No.:

09/483,881

Group Art Unit:

2812

Filed:

January 18, 2000

Docket:

303.672US1

Title:

SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

INFORMATION DISCLOSURE STATEMENT

MS RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

Filing Date: January 18, 2000

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Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's belowsigned representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal

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INFORMATION DISCLOSURE Complete if Known 09/483,881 STATEMENT BY APPLICANT (Use as many steet) as necessary)

MAY 1 6 2005 **Application Number** January 18, 2000 **Filing Date First Named Inventor** Ahn, Kie 2812 **Group Art Unit** Nguyen, Ha **Examiner Name** Attorney Docket No: 303.672US1 Sheet 1 of 1

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PTO/SS/05P(10-0 Approved for use through 10/31/2002, OMB 651-003 US Patent & Tredemark Office: U.S. DEPARTMENT OF COMMERC

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MFORMATION DISCLOSURE
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(Use as many sheets as necessary);

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First Named Inventor Ahn, Kie

Group Art Unit 2812

Examiner Name Nguyen, Ha

Sheet 1 of 1

Attorney Docket No: 303.672US1

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Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T
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EXAMINER

DATE CONSIDERED